

WHAT IS CLAIMED IS:

1. A method of introducing resin for an electronic component, using an apparatus including a die for introducing the resin for the electronic component to introduce melted resin material between each of a plurality of semiconductor chips mounted on a substrate and a surface of said substrate, wherein each of said plurality of semiconductor chips has an upper surface in contact with a mold release film, and with said upper surface's height and inclination considered, via said film said semiconductor chips have their respective upper surfaces individually subjected to equal pressure, while said melted resin material is introduced between each of said plurality of semiconductor chips and the surface of said substrate.

2. An apparatus introducing resin for an electronic component, comprising means capable of performing the method as recited in claim 1.